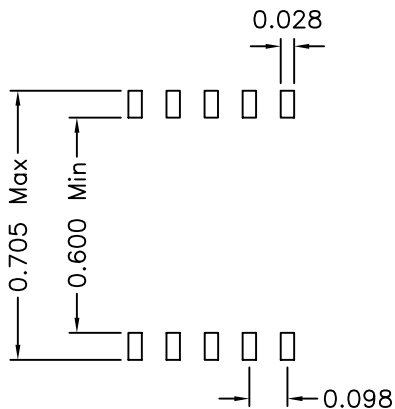
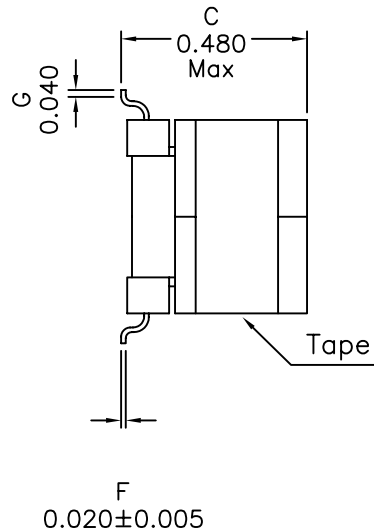
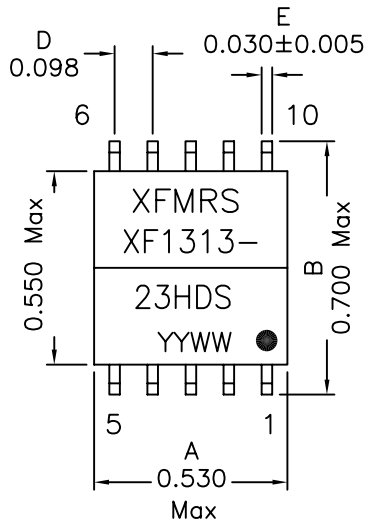
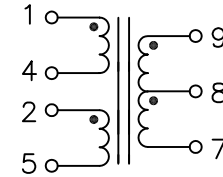


## 1. Dimensions:



Suggested PCB Layout

## 2. Schematic:



## 3. Electrical Specifications: @25°C

- OCL: Pins 1-5 1.50mH±10% @10KHz 1.0V, 0mADC, Ls (Tie Pins 2-4)  
 OCL: Pins 1-5 1.50mH±10% @10KHz 1.0V, 80mAdc, Ls (Tie Pins 2-4)  
 LL: Pins 1-5 17uH Max @100KHz 100mV, Ls (Tie Pins 2-4, Pins 9-7)  
 TURNS RATIO: (1-5):(9-7) = 2CS:1CT±2%, (Tie Pins 2-4)  
 DC Res.: Pins 1-4 1.85 Ohms±10%  
 DC Res.: Pins 2-5 1.85 Ohms±10%  
 DC Res.: Pins 9-7 1.34 Ohms±10%  
 THD: 70dB Max @7KHz, +16dBm at output, 135 ohm load,  
 33.75 ohm input, 0/80Adc, Tie Pins 2-4  
 LB: 40dB Min. @20KHz-300KHz, 34 Ohm Load  
 Hipot: 1900Vac Pin1-9 & Pin2-9  
 Designed to reflect 135 Ohms on the Line side with  
 33.75 Ohms on the IC side.

### Notes:

- Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
- Flammability: UL94V-0
- ASTM oxygen index: > 28%
- Insulation System: 155°C. UL file E151556
- Operating Temperature Range: -40°C to +85°C
- UL1950 approved to Supplementary Insulation requirements for a working voltage up to 300V, file #E165866.

DOC. REV: B/1

XFMRS Inc	Title: HDSL2 Xfmr		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XF1313-23HDS	REV. B
	DWN.	李小锋	Jun-06-02
	CHK.	廖玉坤	Jun-06-02
	APP.	Isaiah M	Jun-06-02